

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Akihiro Mano et al.

Confirmation No.: 4883

Application No.: 10/710,884

Filed: August 10, 2004

Art Unit: 1725

For: METHOD OF SOLDERING
SEMICONDUCTOR PART AND MOUNTED
STRUCTURE OF SEMICONDUCTOR PART

Examiner: L. R. Edmondson

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated July 25, 2006, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.

Fees for excess independent claims have been provided by separate Deposit Account authorization.